



Material Content Data Sheet



Sales Product Name		IPU50R950CE		Issued		2. August 2018		
MA#		MA001507194						
Package		PG-TO251-3-345		Weight*		385.32 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.820	0.47	0.47	4723	4723
leadframe	non noble metal	iron	7439-89-6	0.209	0.05		541	
	inorganic material	phosphorus	7723-14-0	0.063	0.02		162	
	non noble metal	copper	7440-50-8	208.238	54.04	54.11	540434	541137
wire	non noble metal	aluminium	7429-90-5	4.619	1.20	1.20	11989	11989
encapsulation	organic material	carbon black	1333-86-4	0.682	0.18		1770	
	plastics	epoxy resin	-	18.411	4.78		47781	
	inorganic material	silicondioxide	60676-86-0	117.283	30.44	35.40	304383	353934
leadfinish	non noble metal	tin	7440-31-5	7.055	1.83	1.83	18309	18309
solder	noble metal	silver	7440-22-4	0.051	0.01		131	
	non noble metal	tin	7440-31-5	0.041	0.01		105	
	non noble metal	lead	7439-92-1	1.935	0.50	0.52	5021	5257
heatspreader	non noble metal	iron	7439-89-6	0.025	0.01		65	
	inorganic material	phosphorus	7723-14-0	0.007	0.00		19	
	non noble metal	copper	7440-50-8	24.879	6.46	6.47	64567	64651
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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